



100V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D T _C = +25°C
100V	9.5mΩ @ V _{GS} = 10V	48A

Features and Benefits

- 100% Unclamped Inductive Switch (UIS) Test in Production
- High Conversion Efficiency
- Low R_{DS(ON)} Minimizes On State Losses
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/guality/product-definitions/

Description and Applications

This new generation N-channel enhancement mode MOSFET is designed to minimize R_{DS(ON)} yet maintain superior switching performance. This device is ideal for use in notebook battery power management and load switch.

- Backlighting
- Power Management Functions
- DC-DC Converters

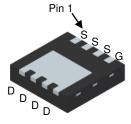
Mechanical Data

- Case: V-DFN3333-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Below Diagram
- Terminals: Finish –NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (4)
- Weight: 0.03 grams (Approximate)

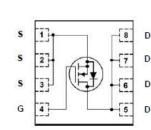
V-DFN3333-8 (Type B)



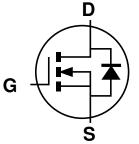




Bottom View



Top View Internal Schematic



Equivalent Circuit

Ordering Information (Note 4)

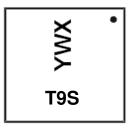
Part Number	Case	Packaging
DMT10H009SCG-7	V-DFN3333-8 (Type B)	2000/Tape & Reel
DMT10H009SCG-13	V-DFN3333-8 (Type B)	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information



T9S = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 0 = 2020)

W = Week (ex: a = Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

Year	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030
Code	9	0	1	2	3	4	5	6	7	8	9	0

Week	1-26	27-52	53
Code	A-Z	a-z	Z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	T	U	V	W	X	Υ	Z

Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage		V _{DSS}	100	V	
Gate-Source Voltage			Vgss	±20	V
Continuous Drain Current, V _{GS} = 10V (Note 6)	Steady State	T _A = +25°C T _A = +70°C	I _D	14 11	А
Continuous Drain Current, V _{GS} = 10V	ID	48 38	А		
Maximum Continuous Body Diode Forward Curr	ent (Note 6)		Is	48	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle =	1%)	I _{DM}	198.5	Α	
Pulsed Body Diode Continuous Current (10µs P	ulse, Duty Cy	Ism	198.5	Α	
Avalanche Current, L = 0.3mH (Note 8)		las	27	Α	
Avalanche Energy, L = 0.3mH (Note 8)		Eas	109.4	mJ	

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	PD	1.3	W
Thermal Resistance, Junction to Ambient (Note 5)	RеJA	99	°C/W
Total Power Dissipation (Note 6)	PD	2.7	W
Thermal Resistance, Junction to Ambient (Note 6)	RеJA	46	°C/W
Thermal Resistance, Junction to Case	R _θ JC	3.7	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout. Notes:

6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

7. Short duration pulse test used to minimize self-heating effect.

8. Guaranteed by design. Not subject to product testing.

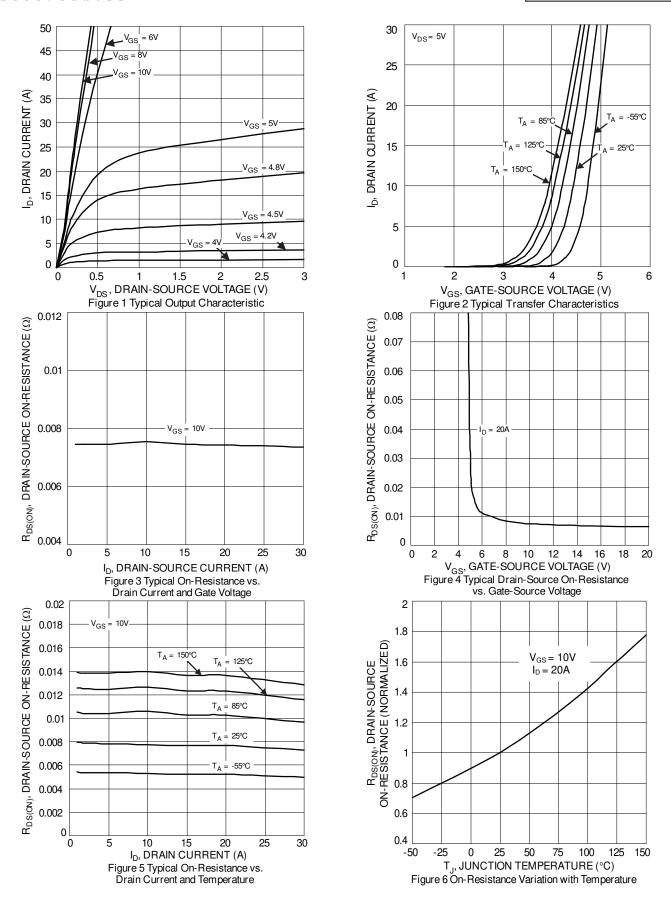


Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

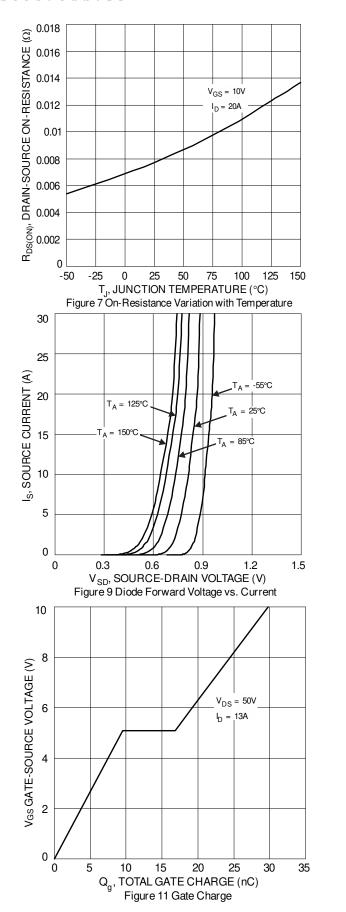
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						·
Drain-Source Breakdown Voltage	BVDSS	100	_	_	V	$V_{GS} = 0V$, $I_D = 1mA$
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 80V, V_{GS} = 0V$
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	2	_	4	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
Static Drain-Source On-Resistance	RDS(ON)	_	7.5	9.5	mΩ	V _{GS} = 10V, I _D = 20A
Diode Forward Voltage	V_{SD}	_	0.8	1.2	V	$V_{GS} = 0V, I_{S} = 20A$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss	_	2085	_		V 50V V 0V
Output Capacitance	Coss	_	609	_	pF	$V_{DS} = 50V$, $V_{GS} = 0V$ f = 1MHz
Reverse Transfer Capacitance	Crss	_	13	_		
Gate Resistance	R_g		1.7	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge	Qg	_	30	_		V 50V L 40A
Gate-Source Charge	Qgs	_	9.5	_	nC	$V_{DD} = 50V, I_{D} = 13A,$ $V_{GS} = 10V$
Gate-Drain Charge	Qgd	_	7.3	_		VGS = 10 V
Turn-On Delay Time	tD(ON)	_	9.7	_		
Turn-On Rise Time	t _R	_	13.7	_		$V_{DD} = 50V, V_{GS} = 10V,$
Turn-Off Delay Time	tD(OFF)	_	25.1	_	ns	$I_D=13A,\ R_g=6\Omega$
Turn-Off Fall Time	t _F	_	17.3	_		
Reverse Recovery Time	trr	_	45	_	ns	1 404 -11/-14 4004/
Reverse Recovery Charge	Qrr	_	68	_	nC	I _F = 13A, di/dt = 100A/μs

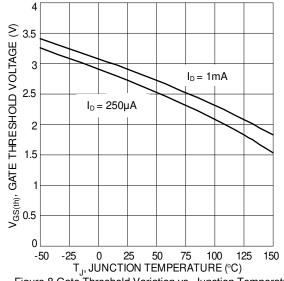
7. Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing. Notes:

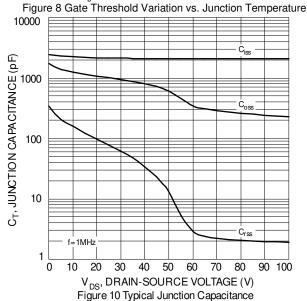


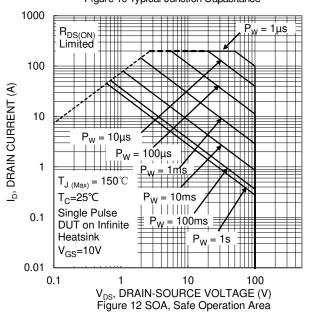














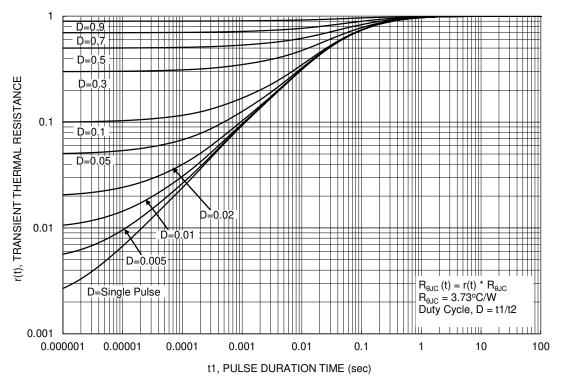


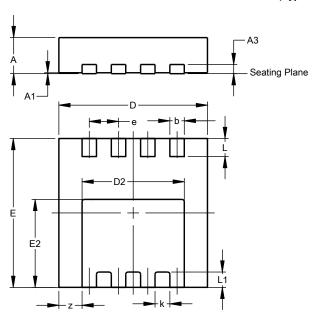
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

 $Please see \ http://www.diodes.com/package-outlines.html \ for \ the \ latest \ version.$

V-DFN3333-8 (Type B)

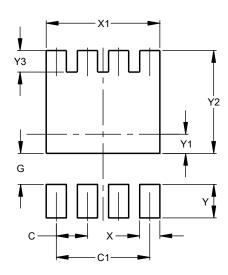


V-DFN3333-8 (Type B)						
Dim	Min	Тур				
Α	0.75	0.85	0.80			
A 1	0.00	0.05	0.02			
A3			0.203			
b	0.27	0.37	0.32			
D	3.25	3.35	3.30			
D2	2.17	2.37	2.27			
Е	3.25	3.35	3.30			
E2	1.85	2.05	1.95			
е	-	-	0.65			
k		-	0.33			
L	0.35	0.45	0.40			
L1			0.34			
Z			0.515			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

V-DFN3333-8 (Type B)



Dimensions	Value (in mm)
С	0.650
C1	1.950
G	0.650
X	0.420
X1	2.370
Y	0.700
Y1	0.400
Y2	2.150
Y3	0.450



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